

L Number	Hits	Search Text	DB	Time stamp
3	20	"529879"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 15:53
4	117	hewlett and (slot\$3 adj substrate\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 15:54
5	20	("5317346"   "5387314"   "5519423"   "5751317"   "5980017"   "6003986"   "6019457"   "6039437"   "6053599"   "6062681"   "6109744"   "6113223"   "6132033"   "6161923"   "6199980"   "6224197"   "6270198"   "6280642"   "6299673"   "6331055"   "2001/0003460").PN.	USPAT	2004/08/02 15:55
6	1		USPAT	2004/08/02 15:57
7	1		USPAT	2004/08/02 15:58
8	1		USPAT	2004/08/02 15:58
9	1		USPAT	2004/08/02 15:58
10	1		USPAT	2004/08/02 16:00
11	1		USPAT	2004/08/02 16:00
12	1		USPAT	2004/08/02 16:01
13	1		USPAT	2004/08/02 16:01
14	1		USPAT	2004/08/02 16:02
15	1		USPAT	2004/08/02 16:02
-	2	6672712.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 10:53
-	10687	(substrate with thick\$) and ((trench\$ slot\$) with surface\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:03
-	218	((substrate with thick\$) and ((trench\$ slot\$) with surface\$)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:18
-	322	(substrate with thick\$) and (axis same ((trench\$ slot\$) with surface\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:18
-	16	((substrate with thick\$) and (axis same ((trench\$ slot\$) with surface\$))) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:25
-	0	20040085408.URPN.	USPAT	2004/06/10 16:25
-	11	("1597487"   "2672072"   "3349174"   "3441948"   "3465352"   "3534166"   "3549826"   "3720784"   "3732363"   "3811009"   "3836225").PN.	USPAT	2004/06/10 16:27
-	20	("5317346"   "5387314"   "5519423"   "5751317"   "5980017"   "6003986"   "6019457"   "6039437"   "6053599"   "6062681"   "6109744"   "6113223"   "6132033"   "6161923"   "6199980"   "6224197"   "6270198"   "6280642"   "6299673"   "6331055"   "2001/0003460").PN.	USPAT	2004/06/10 16:28
-	3	("5006202"   "6107209"   "6273557").PN.	USPAT	2004/06/10 16:30
-	24	("5066357"   "5317346"   "5361087"   "5378137"   "5441593"   "5449630"   "5588597"   "5658471"   "5719604"   "5786988"   "5820919"   "5847725"   "5910679"   "5953029"   "5988786"   "6020270"   "6106096"   "6107158"   "6133926"   "6142611"   "6184570"   "6315397"   "6331055"   "6348396"   "2001/0023979").PN.	USPAT	2004/06/10 16:31
-	21	("5317346"   "5387314"   "5519423"   "5751317"   "5980017"   "6003986"   "6019457"   "6039437"   "6053599"   "6062681"   "6109744"   "6113223"   "6132033"   "6161923"   "6199980"   "6224197"   "6270198"   "6273557"   "6280642"   "6299673"   "6331055"   "2001/0003460").PN.	USPAT	2004/06/10 16:31

-	1	(substrate near (trench with (hole\$1 slot\$1))) and inkjet	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:05
-	5	(substrate near (trench with (hole\$1 slot\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:37
-	278	silverbrook-\$.in. and 347/54.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	3	(silverbrook-\$.in. and 347/54.ccls.) and (substrate near chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	10	(silverbrook-\$.in. and 347/54.ccls.) and (substrate near channel\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:39
-	635	silverbrook-\$.in. and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	3	(silverbrook-\$.in. and 347/\$.ccls.) and (substrate near chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	308	(silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:41
-	233	((silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)) and (hole\$1 slot\$1 trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:41
-	229	((((silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)) and (hole\$1 slot\$1 trench)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 11:09
-	8869	(semiconductor with (slot\$3 etch\$3 hole\$1)) same trench	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 11:10
-	7429	(semiconductor with (slot\$3 etch\$3 hole\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:54
-	7	((semiconductor with (slot\$3 etch\$3 hole\$1) with trench)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 13:30
-	10	("3621442"   "3941629"   "4028945"   "4079508"   "4203128"   "4347976"   "4432007"   "4516148"   "4581624"   "4637071").PN.	USPAT	2004/07/15 11:16
-	15	("4680859"   "4862197"   "4866460"   "5016023"   "5098503"   "5133495"   "5160945"   "5203075"   "5369880"   "5442384"   "5453581"   "5534898"   "5589865"   "6099109"   "6325548").PN.	USPAT	2004/07/15 11:18
-	14	("4680859"   "4862197"   "4866460"   "5016023"   "5098503"   "5133495"   "5160945"   "5203075"   "5369880"   "5442384"   "5453581"   "5534898"   "5589865"   "6099109").PN.	USPAT	2004/07/15 11:21
-	8	("5159353"   "5665249"   "5710070"   "5774148"   "5783474"   "5841452"   "5850241"   "5900894").PN.	USPAT	2004/07/15 11:22

-	91	substrate\$1 with slot\$1 with trench	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 13:31
-	889	(semiconductor with (slot\$3 passage\$1 groove\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	0	((semiconductor with (slot\$3 passage\$1 groove\$1) with trench)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:54
-	915	(semiconductor with (slot\$3 slit\$1 passage\$1 groove\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	64	((semiconductor with (slot\$3 slit\$1 passage\$1 groove\$1) with trench)) and microns	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	2	5953029.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 10:54
-	2	5441593.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 12:00